



08-15-07

Express Mail No. EU313733816US
Attorney Docket No.: AM-8408.P1

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

IN RE APPLICATION OF: Zhenjiang Cui

§ GROUP ART UNIT: Unknown

SERIAL NO.: 10/629,071

§
§ EXAMINER: Unknown

FILED: July 28, 2003

§
§

FOR: METHOD OF PREPARING A SAMPLE
OF A SEMICONDUCTOR STRUCTURE
FOR ADHESION TESTING

§
§
§ Attorney Docket No.: AM-8408.P1

Date: August 13, 2003

INFORMATION DISCLOSURE STATEMENT
TRANSMITTAL LETTER

Hon. Commissioner for Patents
P.O. Box 1450
Alexandria, Virginia 22313-1450

Sir:

Applicants are submitting the subject Information Disclosure Statement under 37 CFR § 1.97(b)(1). This Information Disclosure Statement is being submitted within three (3) months of the filing date of the subject application.

CERTIFICATE OF MAILING UNDER 37 CFR § 1.10

I hereby certify that this paper is being deposited with the U.S. Postal Service on the date shown below with sufficient postage as U.S. EXPRESS MAIL NO. EU313733816US in an envelope addressed to: Mail Stop DD, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Date: August 13, 2003

Shirley L. Church
Shirley L. Church, Reg. No. 31,858

Applicants do not believe that any fee is due in connection with the filing of this Information Disclosure Statement under 37 CFR § 1.97(b)(1). However, in the event that any additional fee is due, the Commissioner is hereby authorized to charge Deposit Account No. 50-1512 of Shirley L. Church, Sunnyvale, California, in the amount of such fee.

This transmittal letter is submitted in duplicate for accounting purposes.

Respectfully submitted,



Shirley L. Church
Registration No. 31,858
Attorney for Applicants

Correspondence Address:
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FORM PTO-1449
(Equivalent)

U.S. Department of Commerce
Patent and Trademark Office

U.S. Application Serial No.
10/629,071

Atty. Docket No.
AM-8408.P1

INFORMATION DISCLOSURE STATEMENT BY APPLICANT

Zhenjiang Cui
Applicants

(Use several sheets if necessary)

July 28, 2003
Filing Date

Unknown Group

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, etc.)

- R. H. Dauskardt et al., "Adhesion and Debonding of Multi-Layer Thin Film Structures", *Engineering Fracture Mechanics*, 61(1), pp. 141 - 162 (1998);.
- M. Lane et al., "Adhesion and Reliability of Copper Interconnects with Ta and TaN Barrier Layers", *J. Mat. Res.*, 15(1), pp. 203 - 211 (2000).
- Q. Ma et al., "Quantitative Measurement of Interface Fracture Energy in Multi-Layer Thin Film Structures", *Proceedings of MRS Annual Meeting*, San Francisco, CA, pp. 3 - 14 and 91 - 96 (1995).

Examiner	Date Considered
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Examiner: Initial if citation considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.